

/ Descriptions

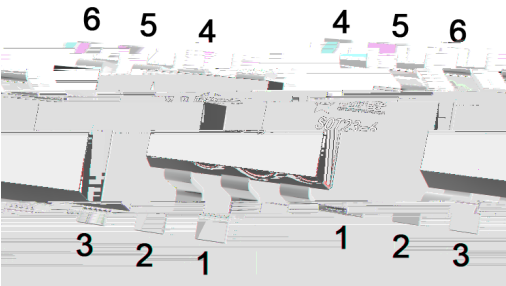
SOT23-6 P
P- CHANNEL MOSFET in a SOT23 -6 Plastic Package.

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$V_{DS}=-60V$; $I_D=-3A$
 $R_{DS(on)1}@-10V \leq 100m\Omega$ (Type.83m Ω)
 $R_{DS(on)2}@-4.5V \leq 130m\Omega$ (Type.100m Ω)
HF Product.

PWM
PWM application & Load switch.

/ Equivalent Circuit



PIN1 D PIN 2 D PIN 3 G PIN 4 S PIN 5 D PIN 6 D

/ Marking

See Marking Instructions.

BRCS1C0P06MF

Rev.B Aug.-2024



蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DSS}	-60	V
Gate–Body Leakage Voltage	V_{GSS}	± 20	V
Drain Current – Continuous	I_D	-3	A
Pulsed Drain Current	I_{DM}	-16	A
Power Dissipation	P_D	1.4	W

/ Electrical Characteristic Curve

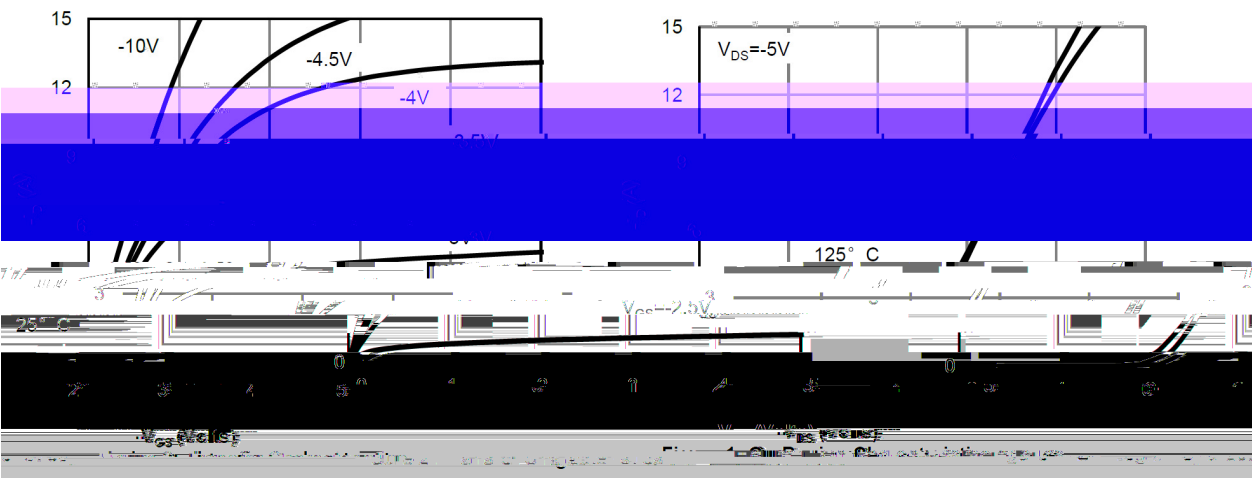
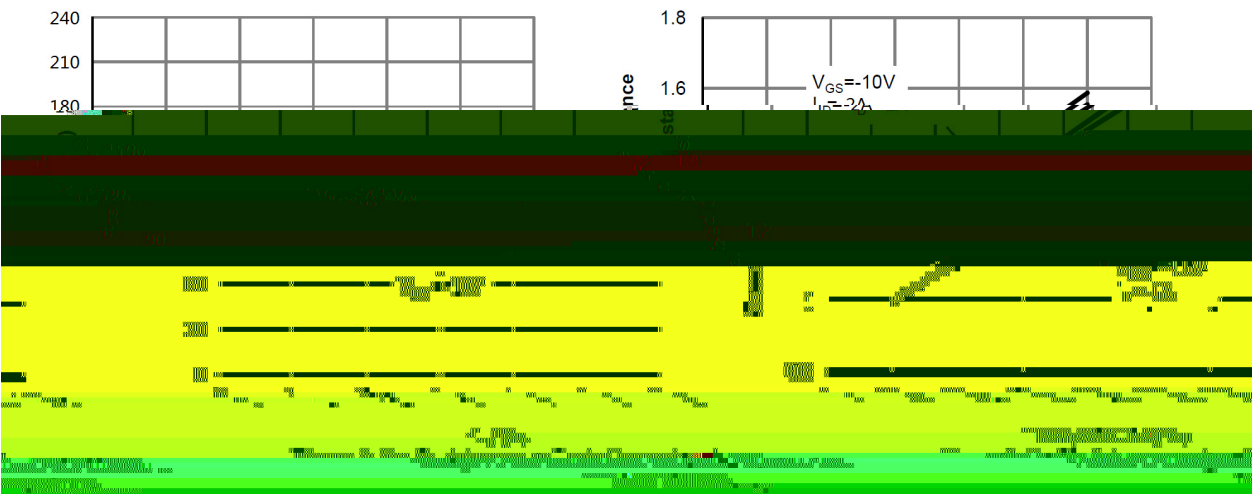
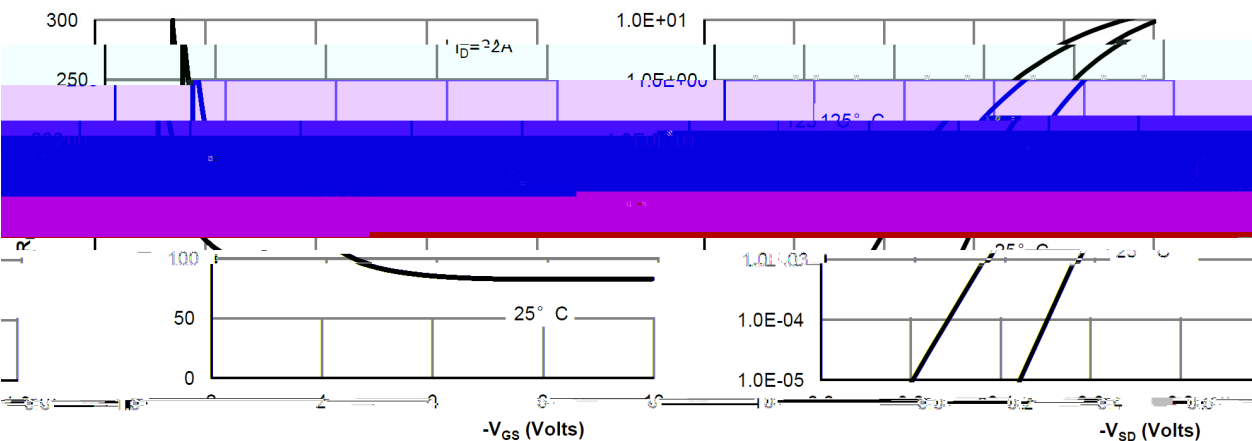
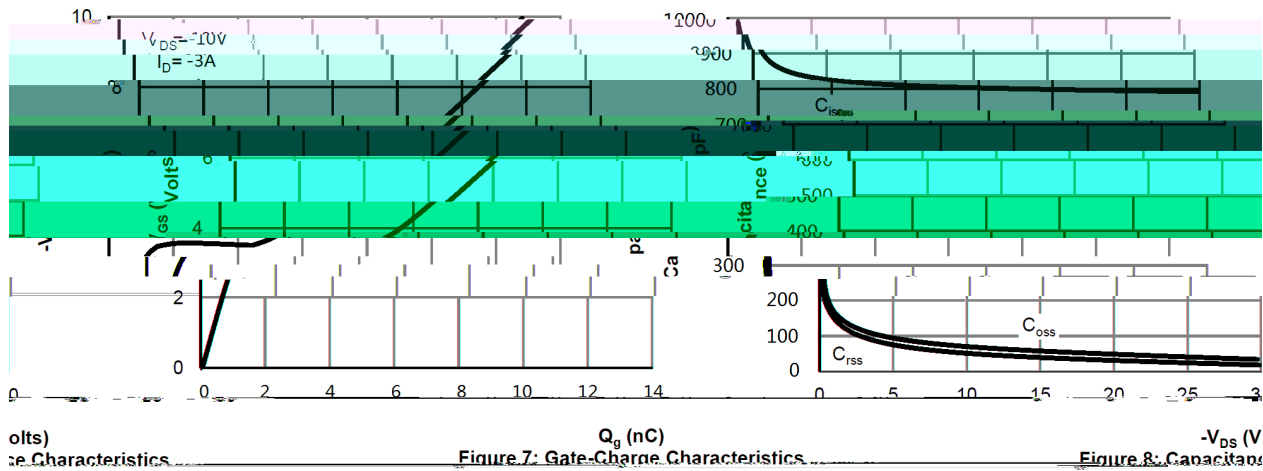
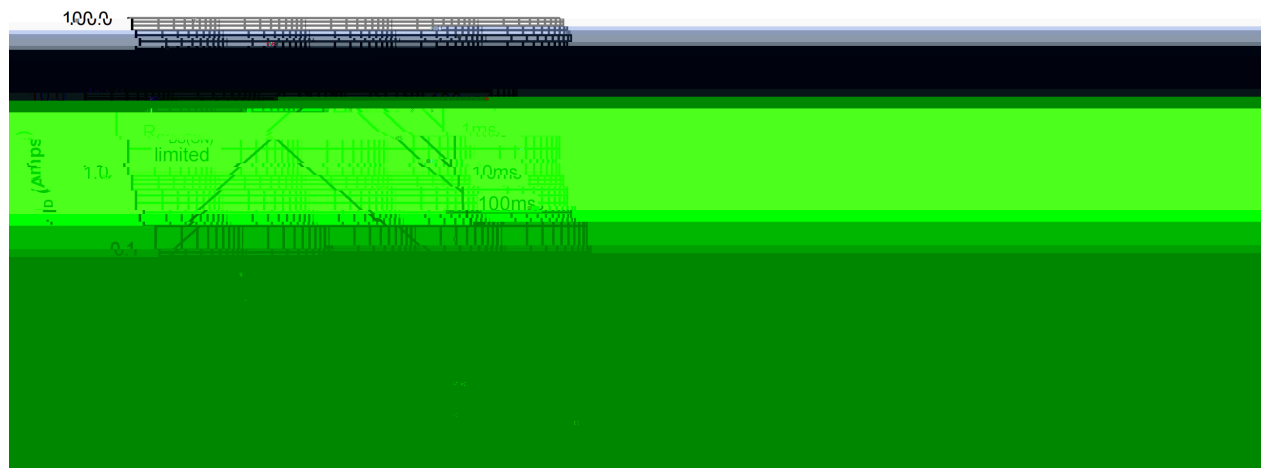
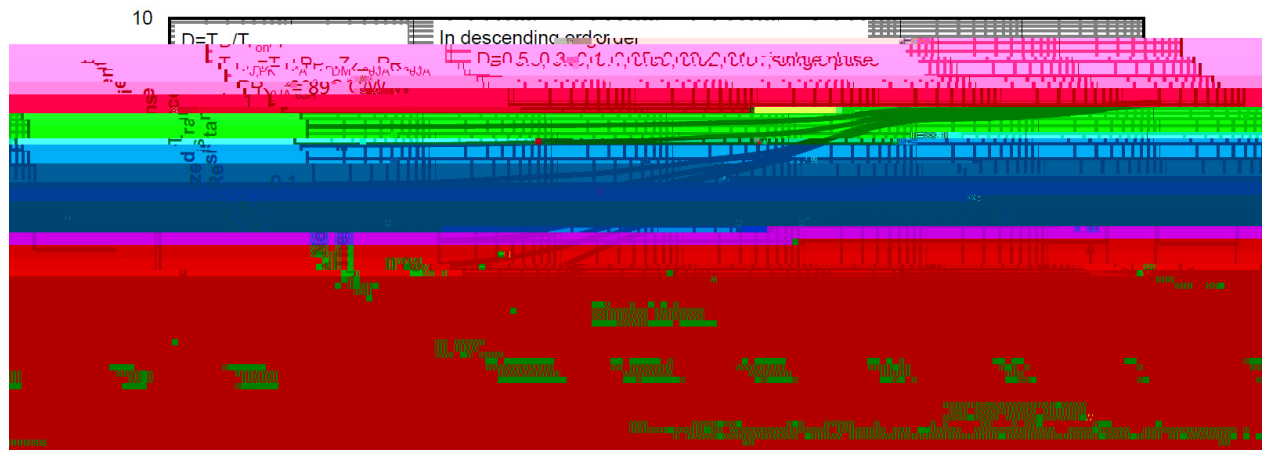


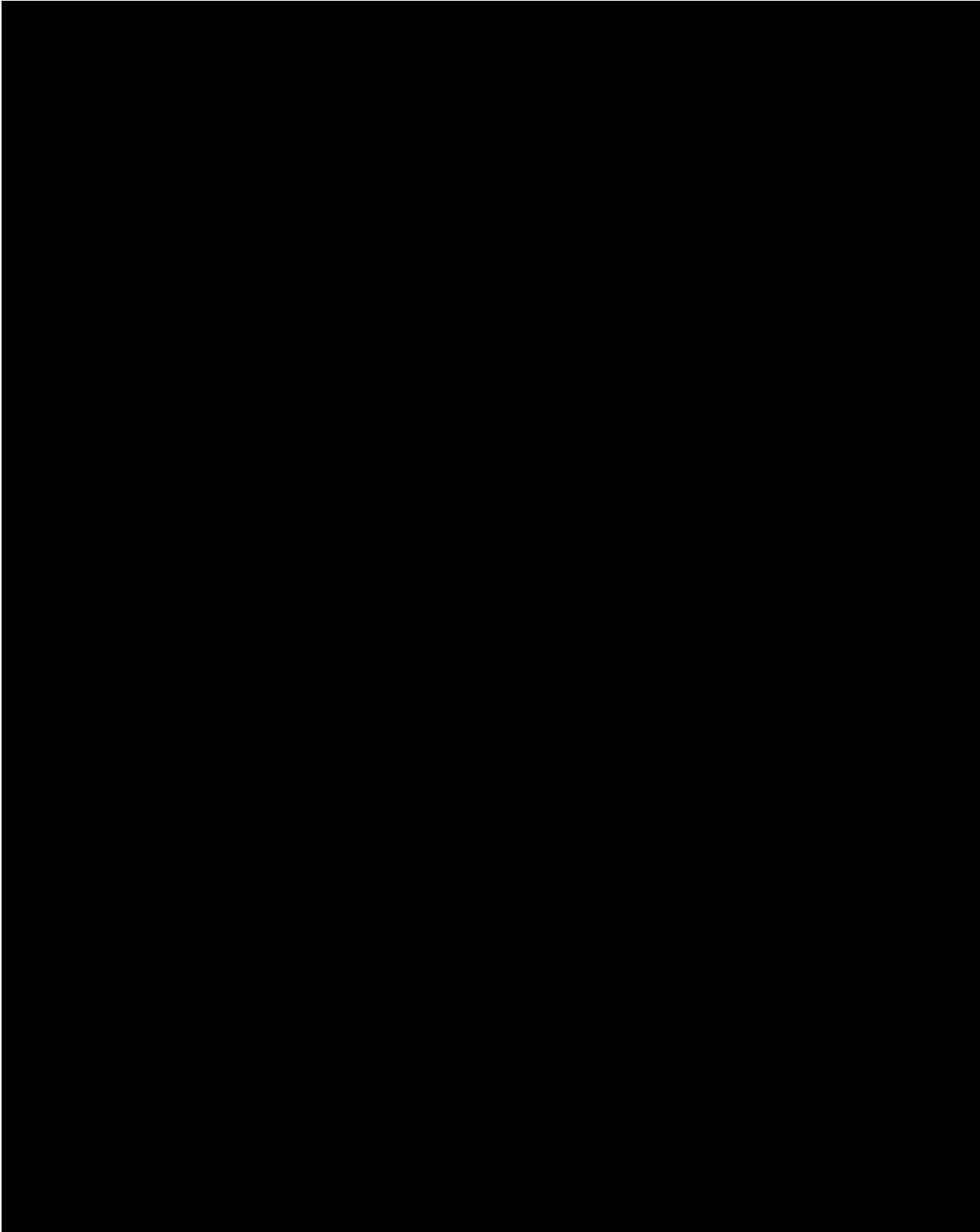
Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristic

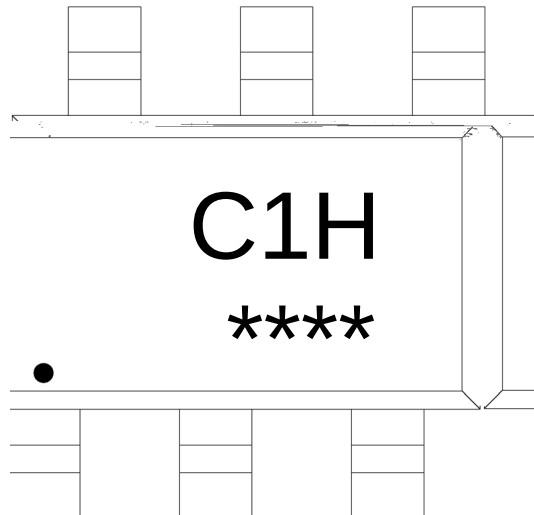
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



C1:

H

Note:

C1: Product Type Code

H: Company Code

**** Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- Note:
- 1

150 180 60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5 5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm ³)
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